

LISTING OF THE CLAIMS

This listing of claims is for reference purposes only. No amendments have been made herein.

1. (Previously Presented) A method for manufacturing an organic electroluminescent display device, comprising: applying an arrangement of layers to a substrate such that first conductors extend in a first direction and second conductors extend in a second direction, providing between crossings of the first and second conductors an organic electroluminescent compound which, under the influence of a voltage, emits light, the substrate being manufactured from plastic and having a surface structure which forms a boundary for at least a number of the layers which are applied, applying a first conductive layer by a layer application process, the surface structure of the plastic substrate being provided with a shadowing structure which is such that with the layer application process, parts of the shadowing structure are substantially not covered with the first conductive layer, the shadowing structure being such that the electrical resistance prevailing there is larger than the resistance in the rest of the first conductive layer.

2. (Previously Presented) A method according to claim 1, wherein the manufacture of the substrate comprises an infection molding process.

3. (Original) A method according to claim 2, wherein in the injection molding process use is made of an injection molding mold which is provided with a negative image of the desired surface structure of the substrate.

4. (Previously presented) A method according to claim 1, wherein the manufacture of the substrate comprises embossing, photopolymeric replication or a plastic formation process.

5. (Previously Presented) A method according to claim 1, wherein after the manufacture of the plastic substrate, a first transparent encapsulation layer is applied to the substrate.
6. (Original) A method according to claim 5, wherein the first transparent encapsulation layer is a nitride-oxide-nitride layer (NON-layer).
7. (Previously Presented) A method according to claim 5, wherein the first transparent encapsulation layer is applied by a deposition technique.
8. (Previously Presented) A method according to claim 5, wherein after the application of the first transparent encapsulation layer, the first conductive layer is applied such that a number of parallel first conductors extending in the first direction are provided which are mutually insulated from each other by an insulator, wherein parts of the first conductors extend in pixel pits or sub-pixel pits of the surface structure of the substrate
9. (Original) A method according to claim 8, wherein the layer application process for the first conductive layer is a sputtering process.
10. (Previously Presented) A method according to claim 9, wherein the shadowing structure comprises a number of parallel, narrow and deep grooves, the width and the depth of the grooves being such that at least a part of the side walls and/or the bottom of these grooves are substantially not covered with the first conductive layer in the sputtering process.
11. (Withdrawn – Previously Presented) A method according to claim 8, wherein the first conductive layer is applied by a printing operation.

12. (Previously Presented) A method according to claim 8, wherein after the application of the first conductive layer, at least in the pixel pits or sub-pixel pits, a hole injecting layer is applied.

13. (Withdrawn - Previously Presented) A method according to claim 11, wherein the first conductive layer forms a hole injecting layer in the pixel pits or sub-pixel pits.

14. (Previously Presented) A method according to claim 12, wherein after application of the hole injecting layer a light emitting layer is provided locally in at least the pixel pits or sub-pixel pits.

15. (Previously Presented) A method according to claim 8, wherein at least those parts of the first conductive layer which are not covered with the organic electroluminescent compound and which, in a following process, will be covered by a second conductive layer, are provided with an insulating covering prior to said following process.

16. (Previously Presented) A method according to claim 15, wherein the insulating covering is applied with a printing operation.

17. (Previously Presented) A method according to claim 16, wherein the insulating covering is formed from a UV-curing varnish.

18. (Previously Presented) A method according to claim 16, wherein the deep grooves forming the shadowing structure are filled up with the insulating covering.

19. (Previously Presented) A method according to claim 1, wherein the shape of the surface structure, after application of at least one layer, is adapted by a transforming technique.

20. (Previously Presented) A method according to claim 19, wherein the transforming technique is a local thermal treatment carried out by laser operation or by local infrared irradiation.

21. (Withdrawn - Previously Presented) A method according to claim 1, wherein a relief structure is provided on the substrate already provided with a number of layers for the application of a following layer.

22. (Withdrawn - Previously Presented) A method according to claim 21, wherein the relief structure is provided by a printing operation, while using a curing varnish.

23. (Withdrawn - Previously Presented) A method according to claim 8, wherein after application of the insulator, a relief structure is provided for forming channels extending parallel to each other, wherein the channel direction is perpendicular to said first direction in which the first conductors extend.

24. (Previously Presented) A method according to claim 15, wherein after application of the insulating covering, a second conductive layer is provided such that in a number of parallel second conductors are provided extending in a second direction and which are mutually insulated from each other, while parts of the second conductors extend in pixel pits or sub-pixel pits of the surface structure of the substrate.

25. (Original) A method according to claim 24, wherein the second direction is perpendicular to the first direction.
26. (Previously Presented) A method according to claim 24, wherein the second conductive layer is applied with a printing process.
27. (Previously Presented) A method according to claim 24, wherein the second conductive layer is applied in channels extending parallel to each other.
28. (Previously Presented) A method according to claim 24, wherein, prior to the application of the second conductive layer and after the application of the insulating covering, an electron injecting layer is applied to the substrate.
29. (Previously Presented) A method according to claim 54, wherein the barium layer is applied with a PVD-process.
30. (Previously Presented) A method according to claim 24, wherein after the application of the second conductive layer at least one encapsulation layer is applied.
31. (Previously Presented) A substrate for use in manufacturing an organic electroluminescent display device, the substrate comprising a first conductive layer applied by a layer application process, wherein the substrate comprises plastic and has a surface structure forming a boundary for the first conductive layer, the surface structure comprising a shadowing structure which is such that with the layer application process, parts of the shadowing structure are substantially not covered with the first conductive layer, the shadowing structure being

such that the electrical resistance prevailing there is larger than the resistance in the rest of the first conductive layer.

32. (Original) A substrate according to claim 31, wherein the surface structure comprises a number of pixel pits or sub-pixel pits.

33. (Previously Presented) A substrate according to claim 31, wherein the layer application process is a sputtering process, and parts of the shadowing structure are not covered with the first conductive layer.

34. (Original) A substrate according to claim 33, wherein the shadowing structure comprises a number of parallel, narrow and deep grooves, wherein the width and the depth of the grooves is such that at least a part of the side wells and/or the bottom of these grooves are not covered with the first conductive layer in the sputtering process.

35. (Previously Presented) A substrate according to claim 31, wherein the surface structure is releasing such that it can be taken from a mold which is provided with a negative image of the surface structure.

36. (Previously Presented) A substrate according to claim 31, wherein the substrate is an injection molding product.

37. (Previously Presented) A substrate according to claim 32, wherein, in the pixel pits or sub-pixel pits, a structure is provided which influences generated light passing the structure.

38. (Previously Presented) A substrate according to claim 32, wherein at a side of the substrate remote from the pixel pits or sub-pixel pits, a structure is provided which influences generated light passing the structure.

39. (Previously Presented) A substrate according to claim 37, wherein the structure comprises a Fresnel lens.

40. (Previously Presented) A substrate according to claim 37, wherein the structure has a converging effect on the light issuing through the structure.

41. (Previously Presented) A substrate according to claim 37, wherein the structure has a diverging effect on the light issuing through the structure.

42. (Withdrawn - Previously Presented) A substrate according to claim 32, wherein in the pixel pits or sub-pixel pits a structure is provided, configured to distribute liquid for forming the layers provided in the pixel pits or substantially-pixel pits.

43. (Previously Presented) A substrate according to claim 32, wherein in the pixel pits or sub-pixel pits a contact surface enlarging structure is provided.

44. (Withdrawn - Previously Presented) A substrate according to claim 42, wherein the structure comprises capillary grooves.

45. (Previously Presented) An organic electroluminescent display device comprising a substrate according to claim 31.

46. (Previously Presented) A method according to claim 7, wherein the deposition technique comprises a PVD, CVD or PECVD process.

47. (Withdrawn - Previously Presented) A method according to claim 11, wherein the printing operation comprises inkjet printing, silkscreen printing, electrostatic printing, or thermal transfer printing.

48. (Previously Presented) A method according to claim 12, wherein the hole injecting layer comprises a PDOT-layer.

49. (Previously Presented) A method according to claim 13, wherein the hole injecting layer comprises PDOT-layer.

50. (Previously Presented) A method according to claim 12, wherein the light emitting layer is a PPV layer.

51. (Previously Presented) A method according to claim 16, wherein the printing operation comprises inkjet printing.

52. (Previously Presented) A method according to claim 22, wherein the curing varnish comprises a UV curing varnish.

53. (Previously Presented) A method according to claim 26, wherein the printing process comprises inkjet printing, silkscreen printing, electrostatic printing, or thermal transfer printing.

54. (Previously Presented) A method according to claim 28, wherein the electron injecting layer comprises a calcium, magnesium lithium fluoride, or barium layer.